

Results

We are pleased to report that ASM Pacific Technology Limited and its subsidiaries (the "Group" or "ASM") achieved turnover amounting to HK\$1,846,016,000 in the fiscal year ended 31 December 2002, representing an increase of 18.3% as compared with HK\$1,560,227,000 for the previous year. The Group's consolidated net profit after tax for the year is HK\$284,704,000 after deducting a one-time restructuring cost of HK\$20,000,000 due to relocation of the Hong Kong leadframe plating operation to China; this is 23.1% higher than the previous year's net profit of HK\$231,246,000. Basic earnings per share for the year amounted to HK\$0.75 (2001: HK\$0.61).

Dividend

An interim dividend of HK\$0.36 (2001: HK\$0.36) per share was paid in August 2002. Having established a solid foundation in the microelectronics market over the years, ASM intends to further its organic growth path in the near term through enlarging its market share with diversified, high performance products. There is no short term need for major cash outlay and the Group has also managed to generate positive cash flow in each of the past few years. In view of our strong liquidity and rising equity base, the Board of Directors have decided to recommend a final dividend of HK\$0.64 (2001: HK\$0.64) per share payable on or around 28 April 2003, making a total payment of HK\$1.00 (2001: HK\$1.00) per share for the year ended 31 December 2002. This translates into a 75.2% dividend payout ratio for the combined 2000-2002 periods, and represents a prudent decision to return current excessive cash holdings to our shareholders while continuing to operate the Group with the optimum shareholders' funds.

Review

In a year when all our leading assembly and packaging equipment competitors were in the red and experienced revenue decline, ASM once again outperformed its industry peers, dethroning the industry leader since inception to become the world's number one in the assembly and packaging equipment industry and achieving an 18.3% higher turnover of US\$236.7 million (2001: US\$200 million).

業績

謹此欣然報告，ASM Pacific Technology Limited及其附屬公司（「集團」或「ASM」）於截至二零零二年十二月三十一日止年度錄得營業額為港幣1,846,016,000元，與上年度港幣1,560,227,000元比較，上升百分之十八點三。在扣除因引線框架電鍍工序由香港遷往中國而導致的一次性重組成本港幣二千萬元後，本年度集團的綜合除稅後淨溢利為港幣284,704,000元，較上年度淨溢利港幣231,246,000元增加百分之二十三點一。是年度每股基本溢利為港幣0.75元（二零零一年：港幣0.61元）。

派息

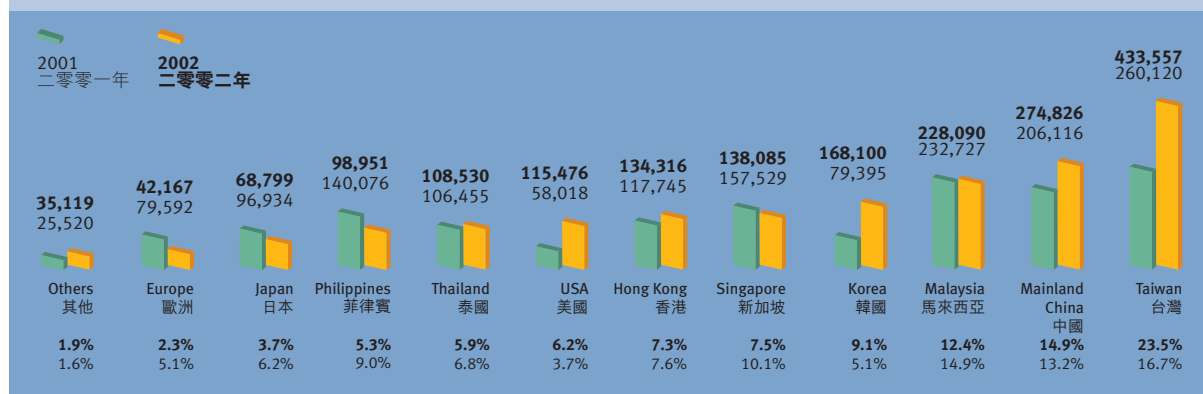
中期股息每股港幣0.36元（二零零一年：港幣0.36元）已於二零零二年八月派發。在過去數年，集團在微電子市場已建立穩固的基礎，未來將致力透過多元化及高性能的產品擴大市場佔有率，積極加快本體增長。集團在短期沒有重大現金開支，並於過往數年維持正現金流量。在擁有充裕的流動資金和股本增加的情況下，董事會現建議派發末期股息每股港幣0.64元（二零零一年：港幣0.64元），於二零零三年四月二十八日左右派發。截至二零零二年十二月三十一日止年度全年合計每股派息為港幣1.00元（二零零一年：港幣1.00元）。於二零零零年至二零零二年間，派息率為百分之七十五點二，充份顯示集團決定將剩餘現金回饋予股東時已作審慎考慮，並預留適量的股本作集團營運之用。

業務回顧

在這一年，當其他著名裝嵌及包裝設備競爭對手均錄得虧損及收益下降，ASM再度超越同儕，取代行業領導者於裝嵌及包裝設備業達至全球第一位，營業額增加百分之十八點三，達二億三千六百七十萬美元（二零零一年：二億美元）。

Turnover by Geographical Location (HK\$'000)

地域分區營業額 (港幣千元)



Review (continued)

Return on capital employed and on sales were 17.1% and 16.0% respectively, in line with previous years in spite of tough market conditions.

This result was largely due to the solid foundation laid over considerable time by the diversification of our products and application markets, an efficient cost structure and successful introductions of new products enlarging our market share. In 2002, sales attributable to our five largest customers combined were less than 25% of the total, with no single customer exceeding 10%, clear evidence of the success of our diversified market strategy.

After depletion of excessive inventory in the electronics supply chain during 2001, semiconductor industry output in 2002 started to reflect true end product demand. Overshadowed by the world's weak economy, war uncertainty and poor stock markets across the globe, lower-priced electronic goods have unfortunately not stimulated as much demand or investment as hoped. Although certain semiconductor companies reported their unit volumes recovering to those of their past peak and an industry analyst - InStat - predicted an 18% unit growth for the industry, most semiconductor industry observers (Dataquest, IC Insights, iSuppli, WSTS, SIA, VLSI Research) concluded that due to pressure on average selling prices there was only 1-2% revenue growth during 2002.

Paralleling this slow upturn, the semiconductor assembly equipment industry came out of its trough and began its recovery late in the first quarter of 2002. Unfortunately, the strong equipment order momentum shown in the second quarter did not continue for the rest of the year, and order inflows weakened sequentially in the following quarters. Customers were extremely cautious in adding capacity, and waited until demands had been firmed up. Most equipment purchases for IC packaging were related to technological advancement such as fine pitch wire bonding and new package types like QFN.

業務回顧 (續)

資本回報率及銷售利潤率分別為百分之十七點一和百分之十六，縱然面對艱難的市場情況，仍與過去數年的表現相若。

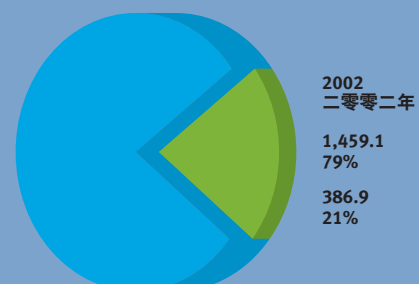
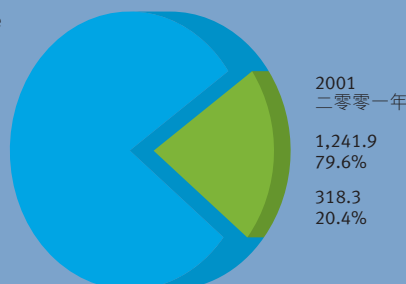
有此成績主要由於集團多年來透過產品及應用市場多元化、有效的成本結構及成功推出新產品以擴大市場佔有率，成功建立起穩固的基礎。於二零零二年，我們五大客戶共佔集團營業額少於百分之二十五，並沒有單一客戶的銷售額佔超過百分之十。這足以證明我們的市場多元化策略是成功的。

電子供應鏈過剩的存貨已於二零零一年被大量消化，使得二零零二年半導體業的產量開始反映真正的最終產品需求。在全球經濟疲弱、戰爭如箭在弦、環球股市表現欠佳，以及電子貨品降價的陰影下，產品需求及投資氣氛並未有如預期中受到刺激。縱使某些半導體公司所公佈的銷售量已回復至其以往高峰時期的水平，及行業分析機構InStat預測行業銷售量將有百分之十八的增長，但大部份的半導體行業研究機構(Dataquest, IC Insights, iSuppli, WSTS, SIA, VLSI Research)均總結認為由於平均售價受壓，二零零二年的收益只有百分之一至二的增長。

相應這緩慢的增長，半導體裝嵌設備行業亦走出谷底，並於二零零二年首季末開始復甦。然而，第二季設備訂單的強勁動力並未能於其後持續，訂單在年內往後的季度內持續疲弱。客戶在增加產能時顯得格外審慎，且留待需求獲得確定後才落實。大部份的集成電路包裝設備訂單均屬於技術提升類別，例如微距焊線及新包裝類別，如QFN。

Turnover by Products (HK\$MILLION)

產品分類營業額 (港幣百萬元)

Equipment
設備Leadframe
引線框架

Review (continued)

After a 70% drop in 2001, all our leading equipment competitors experienced further revenue decline in 2002. In fact, various analysts (Dataquest, VLSI and SEMI) estimated the fall of the assembly and packaging equipment market was in the range of 9-30%. Many people described this slowdown as the steepest and longest in the history of the semiconductor equipment industry.

As with the 1998 and 2001 soft periods, this slowdown created valuable opportunities for ASM to launch market assaults with our new, high performance products and gain market share. Our equipment business, which represented 79% of the Group's turnover in 2002, grew 17.5% last year. We outstripped the competitor who had led the industry since its beginning, becoming the world's number one in the assembly and packaging equipment industry in 2002. In a similar standout result, our leadframe sales rose by 21.6% over the same period, much higher than the market growth of 10.1% according to SEMI. The resilience of our business performance in the face of such major industry fluctuations clearly distinguishes ASM from our competitors, paving our way for further corporate developments in the coming years.

Whilst most of our competitors have been cutting headcount and projects to minimize their haemorrhaging cash flow, ASM in contrast has accelerated our technology and product developments. Last year we actually increased our R&D expenses to HK\$186.98 million (2001: HK\$166.40 million), representing 12.8% (2001:13.4%) of our equipment sales. Launched in mid 2002, our Eagle 60 wire bonder, capable of 35µm fine pitch bonding, further strengthened ASM's leadership position and protected our market turf. In the past few months, the Eagle 60 has run through a number of benchmarking and customer qualifications with existing and new customers, for both integrated device manufacturers (IDMs) and packaging companies (subcons), all with favourable results. While some of these field evaluations are still continuing, volume production has successfully migrated to this new model during the fourth quarter of last year.

Other exciting new products, such as our high speed, innovative IC and discrete die bonders, our precision flip chip bonder, die sorter, matrix test handler and tape & reel finishing system likewise all crossed over to their volume production phase. These new products solidified our premier position in the die and wire bonder markets, as well as widening our customer base by addressing new market segments we did not serve in the past.

業務回顧(續)

繼二零零一年下降百分之七十後，我們所有的具領導性的設備競爭對手在二零零二年的收益均進一步下調。事實上，多個分析機構(Dataquest, VLSI及SEMI)估計裝嵌及包裝設備市場的下調幅度為百分之九至三十。很多人形容這次的放緩為半導體設備行業歷史中最艱辛及最持久的一次。

正如一九九八年及二零零一年的疲弱時期一樣，是次放緩正好為ASM創造寶貴的機會，把我們嶄新及性能超卓的產品推出市場，擴大市場佔有率。我們的設備業務於二零零二年佔集團的營業額百分之七十九，較去年增長百分之十七點五。於二零零二年，我們已超越一直處於行業領導地位的对手，在裝嵌及包裝業內達至全球第一位。同樣突出的是，我們的引線框架銷售於期內上升百分之二十一點六，遠超SEMI所預測百分之十點一的市場增長。面對重大的行業波動，ASM仍能迅速恢復表現，於競爭對手中突圍而出，為未來企業進一步發展鋪路。

正當我們大部份的競爭對手裁減人手、縮減項目規模以盡量降低其現金流出之際，ASM反而加速技術及產品的開發。去年，我們的研發開支實質增加至港幣186,980,000元(二零零一年：港幣166,400,000元)，佔設備銷售額的百分之十二點八(二零零一年：百分之十三點四)。我們於二零零二年中推出的Eagle 60焊線機，可作35µm微距焊線，進一步鞏固ASM的領導地位及市場基礎。在過去數月，Eagle 60已通過現有客戶及新客戶多個基準測試及審定合格，當中包括集成裝置製造商(IDMs)和包裝公司(subcons)，成績令人滿意。部份的實地評估仍在進行當中，而這新型號產品已於去年第四季成功地邁向量產階段。

其他新產品，如高速嶄新的集成電路及獨立管芯焊接機、精密的覆晶焊接機、管芯分類機、距陣測試處理器以及卷軸完成系統(tape and reel finishing system)等已全部進入量產階段。這些新產品強化了我們於管芯焊機及焊線機市場的領導地位，同時擴闊了我們的客戶基礎，覆蓋以往從未涉足的新市場層面。